

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJU55P30
Package Type :	TO-252-2L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.8847%
Lead Frame	Iron	7439-89-6	0.10%	57.9281%
	Phosphorus	7723-14-0	0.2125%	
	Copper	7440-50-8	99.6834%	
	Nickel (Ni)	7440-02-0	0.0041%	
Soft Solder	Lead	7439-92- 1	92.50%	1.1128%
	Tin	7440-31-5	5.00%	
	Silver	7440-22-4	2.50%	
Wire	Al	7429-90-5	99.996%	0.3122%
	Others	/	0.004%	
Mold Compound	Silica	60676-86-0	75.50%	38.4791%
	Epoxy Resin	29690-82-2	13.00%	
	Phenol Resin	9003-35-4	8.00%	
	Fire Retardant	Trade secret	3.00%	
	Carbon black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.99%	1.283%
	Others	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.